

Application No.: 10/034,030

Docket No.: JCLA8482

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of :

HORNG ET AL.

Serial No. : 10/034,030

Filed : 12/19/2001

For : METHOD OF FABRICATING
A CERAMIC SUBSTRATE WITH
A THERMAL CONDUCTIVE PLUG
OF A MULTI-CHIP PACKAGE

Examiner : TRINH, MINH N

Art Unit : 3729

Docket No. : JCLA8482

No fee is believed to be due. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-0710 (Order No. JCLA8482).

AMENDMENT AFTER FINAL

Mail Stop AF
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The Office Action mailed 04/02/2004 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.